

CYStech Electronics Corp.

Spec. No. : C474LB Issued Date : 2009.08.13

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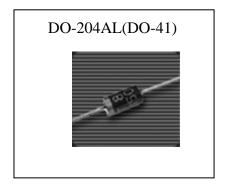
Schottky Barrier Rectifiers Reverse Voltage 20V to 60V Forward Current 1.0 Amperes

SB120 thru SB160

Features

- Metal semiconductor junction with guard ring
- Epitaxial construction
- Low forward voltage drop
- High current capability
- The plastic material carries UL recognition 94V-0
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

Outline



Mechanical Characteristics:

•Case: JEDEC DO-204AL(DO-41) molded plastic

•Terminals: Tin plated axial leads, solderable per MIL-STD-202, method 208

•Polarity: Color band denotes cathode

•Mounting position: Any •Weight : 0.012oz., 0.33grams

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%)

Parameter		Symbol	Туре					Units
			SB120	SB130	SB140	SB150	SB160	Units
Maximum repetitive peak reverse vo	Vrrm	20	30	40	50	60	V	
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	V	
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	V	
Maximum forward voltage at 1A	VF	0.5 0.70				70	V	
Maximum average forward rectified .375"(9.5mm) lead lengths @T _L =100	IF(AV)	1					A	
Peak forward surge current @8.3ms sine wave superimposed on rated loamethod)	IFSM	40				A		
Maximum DC reverse current at	T _J =25°C	T	0.5					mA
rated DC blocking voltage	T _J =100°C	Ir	10					
Typical thermal resistance (Note 1)		RөлL	15				°C/W	
Typical junction capacitance (Note 2)	Сл	150				pF		
Operating junction temperature range	TJ	-55 ~ +125				°C		
Storage temperature range	Tstg	-55 ~ +150				°C		

Note: 1.Thermal resistance, junction to lead.

2.Measured at 1.0MHz and applied reverse voltage of 4.0VDC

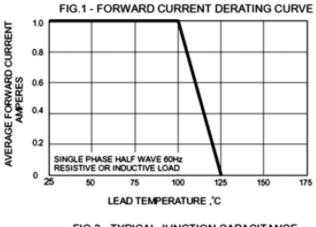


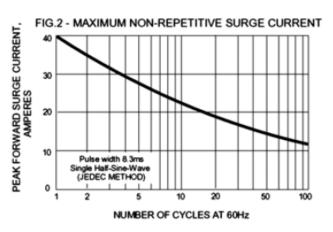
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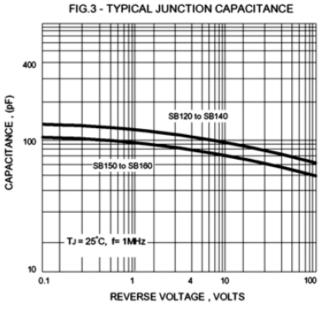
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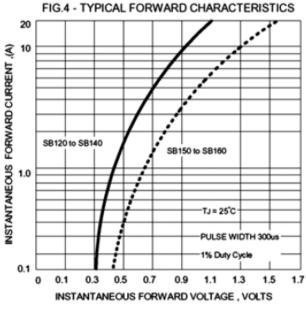
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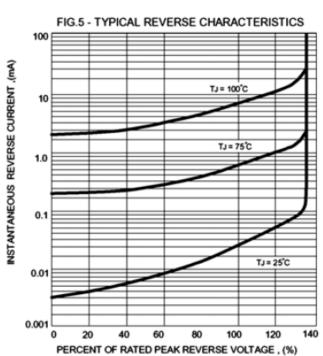
Characteristic Curves











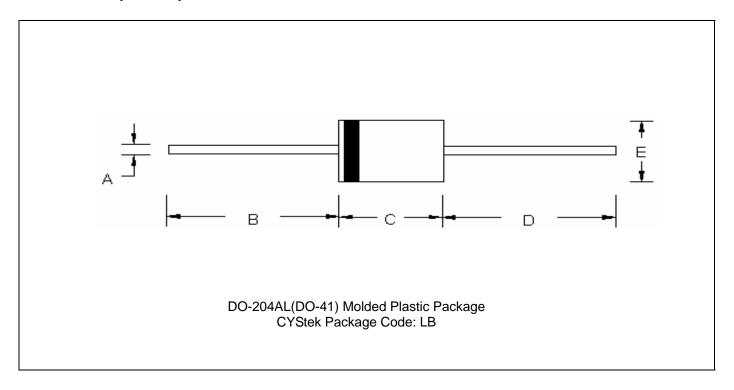


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DO-204AL(DO-41) Dimension



DIM	Inc	hes	Millin	neters	DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.	ווועו	Min.	Max.	Min.	Max.
Α	φ0.0280	φ0.0339	φ0.71	φ0.86	D	1.0000	-	25.40	-
В	1.0000	-	25.40	-	Е	φ0.0787	φ0.1063	φ2.00	φ2.70
С	0.1654	0.2047	4.20	5.20			•		•

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material. 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed.
- Mold Compound : Epoxy resin family, flammability solid burning class: UL94V-0

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